



Initial Product/Process Change Notification

Document #: IPCN26983XA1

Issue Date: 28 Jul 2026

Title of Change:	Update to IPCN26983XA - Wafer Fab and Test Site Change for UFET Trench Products from Mountain Top, USA to Bucheon, Korea and assembly BOM changes (mold compound and lead frame)
Proposed First Ship date:	22 Jan 2027 or earlier if approved by customer
Contact Information:	Contact your local onsemi Sales Office
PCN Samples Contact:	Contact your local onsemi Sales Office. Sample requests are to be submitted no later than 30 days from the date of first notification, Initial PCN or Final PCN, for this change. Samples delivery timing will be subject to request date, sample quantity and special customer packing/label requirements.
Type of Notification:	This is an Initial Product/Process Change Notification (IPCN) sent to customers. An IPCN is an advance notification about an upcoming change and contains general information regarding the change details and devices affected. It also contains the preliminary reliability qualification plan. The completed qualification and characterization data will be included in the Final Product/Process Change Notification (FPCN). This IPCN notification will be followed by a Final Product/Process Change Notification (FPCN) at least 90 days prior to implementation of the change. In case of questions, contact <PCN.Support@onsemi.com>
Marking of Parts/ Traceability of Change:	The changed material can be identified by lot code and date code.
Change Category:	Test Change, Wafer Fab Change, Assembly Change
Change Sub-Category(s):	Material Change, Manufacturing Site Transfer

Sites Affected:

onsemi Sites	External Foundry/Subcon Sites
onsemi Bucheon, Korea	None
onsemi Cebu, Philippines	

Description and Purpose:

This Update Notification is to inform customers of the qualifications of onsemi Bucheon, Korea facility as NEW wafer fab site for UFET Trench Technology and assembly BOM changes (mold compound and lead frame).

FPCNs to be issued in **October of 2026** with first ship date as referenced above from Bucheon fab. If your FPCN approval will extend beyond the proposed first ship date, provide unit requirements for the unchanged material to your onsemi sales representative no later than **May 31, 2026**, by NCNR PO (Last order date for unchanged material).

These bridge quantities will be limited and will be considered on a first-come, first-serve basis. onsemi will work with customers to facilitate the approval of the FPCNs by providing early samples and matching electrical data upon request, prior to the final PCN notices in **October of 2026** to reduce customers' need for additional unchanged material. Early samples are processed according to final process and condition as released in the FPCN. No changes will occur between early samples and after FPCN issuance.

	Before Change Description	After Change Description
FAB Site	Mountain Top, PA, USA	Bucheon, Korea
Back grind Site	Mountain Top, PA, USA	Bucheon, Korea
Probe Site	Mountain Top, PA, USA and Bucheon, Korea	Bucheon, Korea
Wafer size	8 inch	6 inch
Mold Compound change for TO263 only	Showa Denko MP-195	Sumitomo G700HF
OPN naming	No change	-BK suffix added



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Qualification Plan:

QV DEVICE NAME : FDB2710 (QV 1T)

RMS : 98259

PACKAGE : D2PAK

Test	Specification	Condition	Interval
High Temperature Reverse Bias	JESD22-A108	Tj = Max rate Tj for device, bias =100% of rated V (Not to exceed max rated)	1,008 hrs
High Temperature Gate Bias	JESD22-A108	Tj = Max rate Tj for device, Max Vgs	1,008 hrs
High Temperature Storage Life	JESD22-A103	Ta =Max rate storage temp for device	1,008 hrs
Precondition (PC)	J-STD-020, JESD22-A113	IR reflow at 245C or 260(pkg dependant)	-
(PC+) Highly Accelerated Stress Test	JESD22-A110	Temp = 130C, 85% RH, ~ 18.8 psig, bias = 80% of rated V or 100V max	96 hrs
(PC+) Unbiased Highly Accelerated Stress Test	JESD22-A118	Temp = 130C, RH=85%, ~ 18.8 psig	96 hrs
(PC+) Temp Cycling	JESD22-A104	Temp = -55°C to +150°C	1,000 cyc
(PC+) Intermittent Operating Life	MIL STD750, M 1037, AEC Q101	Ta=+25°C, deltaTj=100°C max, 3.5 min Ton=Toff	8,527 cyc

QV DEVICE NAME : FDB5800 (QV 2T)

RMS : 98261

PACKAGE : D2PAK

Test	Specification	Condition	Interval
High Temperature Gate Bias	JESD22-A108	Tj = Max rate Tj for device, Max Vgs	1,008 hrs

QV DEVICE NAME : FDS2734 (QV 3T)

RMS : 98260

PACKAGE : SOIC-8

Test	Specification	Condition	Interval
Precondition (PC)	J-STD-020, JESD22-A113	IR reflow at 245C or 260(pkg dependant)	-
(PC+) Highly Accelerated Stress Test	JESD22-A110	Temp = 130C, 85% RH, ~ 18.8 psig, bias = 80% of rated V or 100V max	96 hrs
(PC+) Unbiased Highly Accelerated Stress Test	JESD22-A118	Temp = 130C, RH=85%, ~ 18.8 psig	96 hrs
(PC+) Temp Cycling	JESD22-A104	Temp = -55°C to +150°C	1,000 cyc
(PC+) Intermittent Operating Life	MIL STD750, M 1037, AEC Q101	Ta=+25°C, deltaTj=100°C max, 2 min Ton=Toff	15,000 cyc



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List of Affected Parts:

Note: Only the standard (off the shelf) part numbers are listed in the parts list. Any custom parts affected by this PCN are shown in the customer specific PCN addendum in the PCN email notification, or on the [PCN Customized Portal](#)

Current Part Number	New Part Number	Qualification Vehicle
FDB035AN06A0	FDB035AN06A0-BK	FDB2710
FDB045AN08A0	FDB045AN08A0-BK	FDB2710
FDB050AN06A0	FDB050AN06A0-BK	FDB2710
FDB060AN08A0	FDB060AN08A0-BK	FDB2710
FDB070AN06A0	FDB070AN06A0-BK	FDB2710
FDB13AN06A0	FDB13AN06A0-BK	FDB2710
FDB16AN08A0	FDB16AN08A0-BK	FDB2710
FDB3632	FDB3632-BK	FDB2710
FDB3652	FDB3652-BK	FDB2710
FDB3682	FDB3682-BK	FDB2710
FDB5800	FDB5800-BK	FDB2710
FDD10AN06A0	FDD10AN06A0-BK	FDB2710
FDD13AN06A0	FDD13AN06A0-BK	FDB2710
FDD16AN08A0	FDD16AN08A0-BK	FDB2710
FDD3672	FDD3672-BK	FDB2710
FDD3682	FDD3682-BK	FDB2710
FDH047AN08A0	FDH047AN08A0-BK	FDB2710
FDH3632	FDH3632-BK	FDB2710
FDM3622	FDM3622-BK	FDB2710
FDMS3572	FDMS3572-BK	FDB2710
FDMS3672	FDMS3672-BK	FDB2710
FDMS5672	FDMS5672-BK	FDB2710
FDP038AN06A0	FDP038AN06A0-BK	FDB2710
FDP047AN08A0	FDP047AN08A0-BK	FDB2710
FDP050AN06A0	FDP050AN06A0-BK	FDB2710
FDP060AN08A0	FDP060AN08A0-BK	FDB2710
FDP070AN06A0	FDP070AN06A0-BK	FDB2710
FDP16AN08A0	FDP16AN08A0-BK	FDB2710
FDP3651U	FDP3651U-BK	FDB2710
FDP3652	FDP3652-BK	FDB2710



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FDP3672	FDP3672-BK	FDB2710
FDP3682	FDP3682-BK	FDB2710
FDP42AN15A0	FDP42AN15A0-BK	FDB2710
FDP5800	FDP5800-BK	FDB2710
FDPF2710T	FDPF2710T-BK	FDB2710
FDS2572	FDS2572-BK	FDB2710
FDS2582	FDS2582-BK	FDB2710
FDS2672	FDS2672-BK	FDB2710
FDS2734	FDS2734-BK	FDB2710
FDS3572	FDS3572-BK	FDB2710
FDS3672	FDS3672-BK	FDB2710
FDS3692	FDS3692-BK	FDB2710
FDS5672	FDS5672-BK	FDB2710
FDS3992	FDS3992-BK	FDB2710
FDP047AN08A0-G	FDP047AN08A0-G-BK	FDB2710
FDP2710	FDP2710-BK	FDB2710
FDB2710	FDB2710-BK	FDB2710
FDP2614	FDP2614-BK	FDB2710
FDB2614	FDB2614-BK	FDB2710
FDMS2734	FDMS2734-BK	FDB2710
FDMS2672	FDMS2672-BK	FDB2710
FDMC2610	FDMC2610-BK	FDB2710
FDP2532	FDP2532-BK	FDB2710
FDB2532	FDB2532-BK	FDB2710
FDP2552	FDP2552-BK	FDB2710
FDB2552	FDB2552-BK	FDB2710
FDMS2572	FDMS2572-BK	FDB2710
FDP2572	FDP2572-BK	FDB2710
FDD2572	FDD2572-BK	FDB2710
FDB2572	FDB2572-BK	FDB2710
FDD2582	FDD2582-BK	FDB2710
FDD120AN15A0	FDD120AN15A0-BK	FDB2710
FDP3632	FDP3632-BK	FDB2710